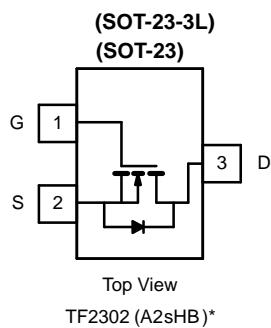




## N-Channel 1.25-W, 2.5-V MOSFET

## PRODUCT SUMMARY

$V_{DS}$ (V)	$r_{DS(on)}$ ( $\Omega$ )	$I_D$ (A)
20	0.065 @ $V_{GS} = 4.5$ V	3.0
	0.090 @ $V_{GS} = 2.5$ V	2.0

ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$  UNLESS OTHERWISE NOTED)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	20	V
Gate-Source Voltage	$V_{GS}$	$\pm 8$	
Continuous Drain Current ( $T_J = 150^\circ\text{C}$ ) <sup>b</sup>	$I_D$	3.0	A
Pulsed Drain Current <sup>a</sup>	$I_{DM}$	10	
Continuous Source Current (Diode Conduction) <sup>b</sup>	$I_S$	1.6	
Power Dissipation <sup>b</sup>	$P_D$	1.25	W
Operating Junction and Storage Temperature Range	$T_J, T_{Stg}$	-55 to 150	°C

## THERMAL RESISTANCE RATINGS

Parameter	Symbol	Limit	Unit
Maximum Junction-to-Ambient <sup>b</sup>	$R_{thJA}$	100	°C/W
Maximum Junction-to-Ambient <sup>c</sup>		166	

## Notes

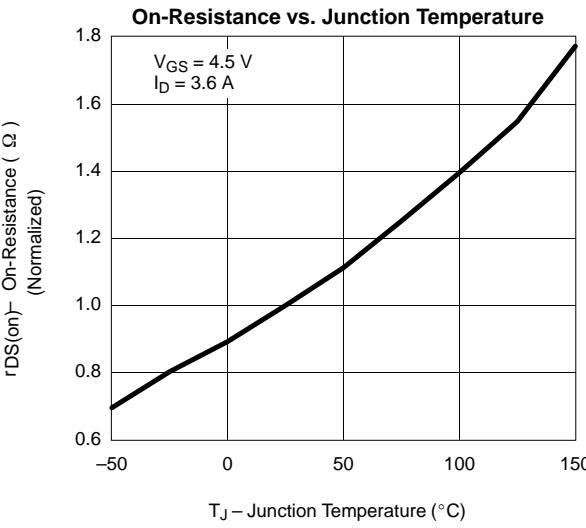
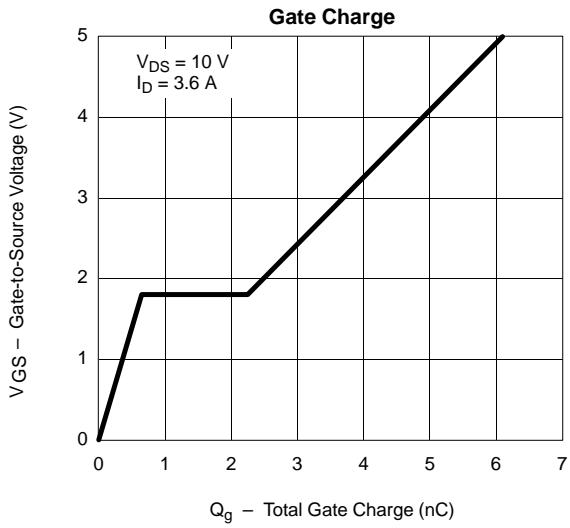
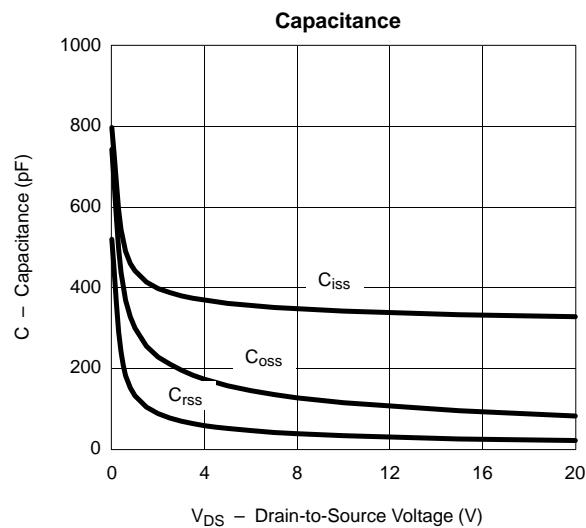
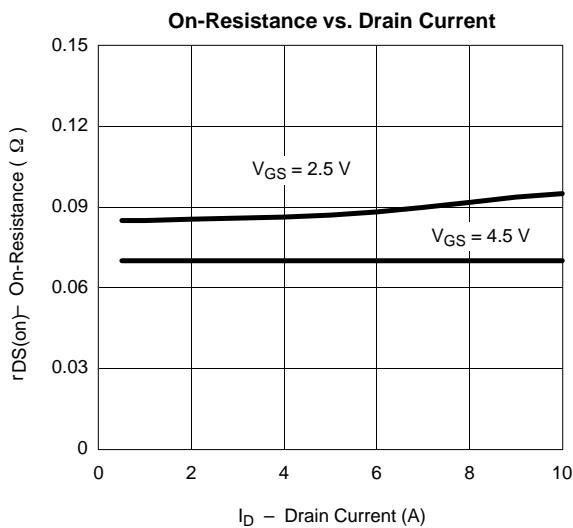
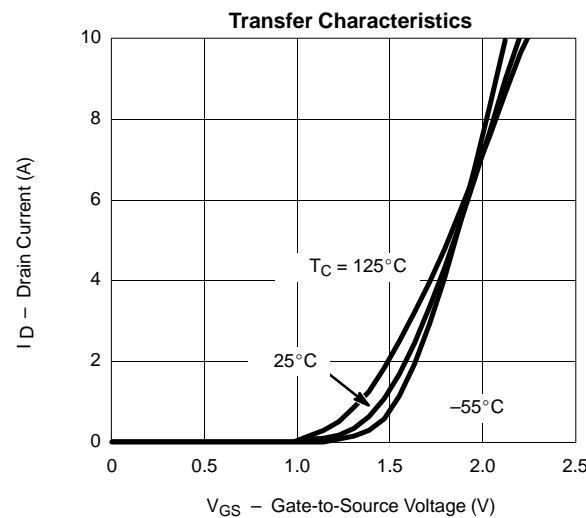
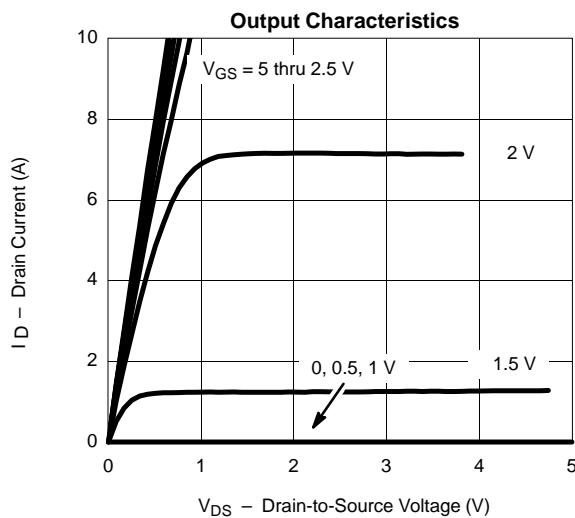
- a. Pulse width limited by maximum junction temperature.
- b. Surface Mounted on FR4 Board,  $t \leq 5$  sec.
- c. Surface Mounted on FR4 Board.

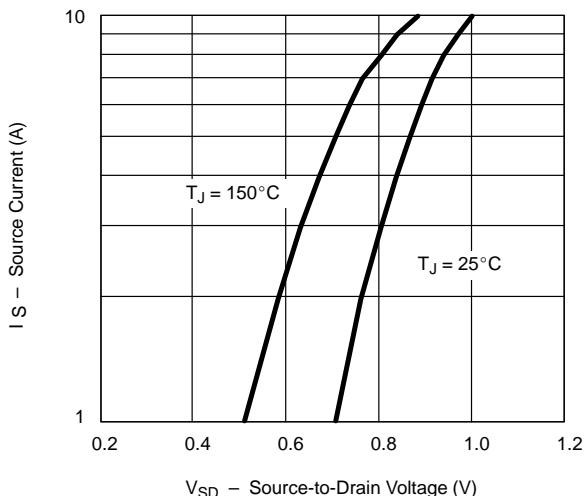
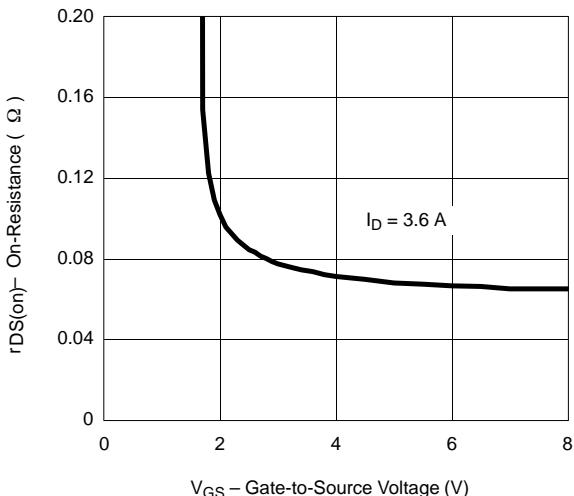
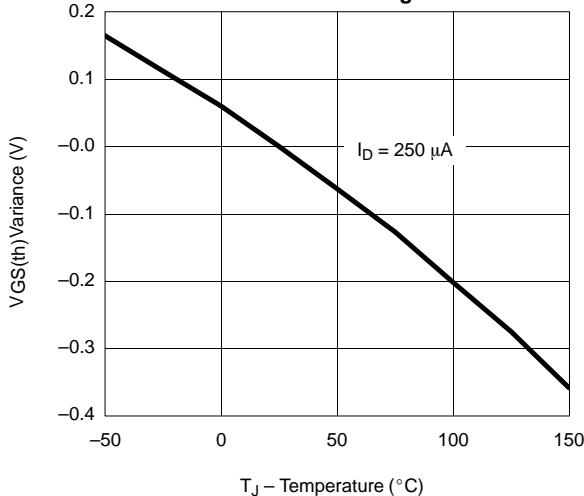
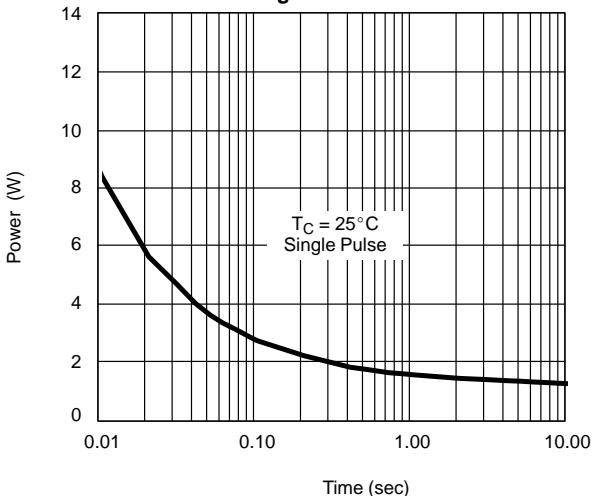
**SPECIFICATIONS ( $T_A = 25^\circ\text{C}$  UNLESS OTHERWISE NOTED)**

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	20			V
Gate-Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	0.5		1.0	
Gate-Body Leakage	$I_{GSS}$	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 16 \text{ V}, V_{GS} = 0 \text{ V}$			50	nA
		$V_{DS} = 16 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 55^\circ\text{C}$				
On-State Drain Current <sup>a</sup>	$I_{D(\text{on})}$	$V_{DS} \geq 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	6			A
		$V_{DS} \geq 5 \text{ V}, V_{GS} = 2.5 \text{ V}$	4			
Drain-Source On-Resistance <sup>a</sup>	$r_{DS(\text{on})}$	$V_{GS} = 4.5 \text{ V}, I_D = 3.0 \text{ A}$		0.060	0.065	$\Omega$
		$V_{GS} = 2.5 \text{ V}, I_D = 2.0 \text{ A}$		0.085	0.090	
Forward Transconductance <sup>a</sup>	$g_{fs}$	$V_{DS} = 5 \text{ V}, I_D = 3.0 \text{ A}$	10			S
Diode Forward Voltage	$V_{SD}$	$I_S = 1.0 \text{ A}, V_{GS} = 0 \text{ V}$			1.28	V
<b>Dynamic</b>						
Total Gate Charge	$Q_g$	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 3.6 \text{ A}$		5.4	10	nC
Gate-Source Charge	$Q_{gs}$			0.65		
Gate-Drain Charge	$Q_{gd}$			1.60		
Input Capacitance	$C_{iss}$	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		340		pF
Output Capacitance	$C_{oss}$			115		
Reverse Transfer Capacitance	$C_{rss}$			33		
<b>Switching</b>						
Turn-On Delay Time	$t_{d(\text{on})}$	$V_{DD} = 10 \text{ V}, R_L = 5.5 \Omega$ $I_D \approx 3.6 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_G = 6 \Omega$		12	25	ns
Rise Time	$t_r$			36	60	
Turn-Off Delay Time	$t_{d(\text{off})}$			34	60	
Fall-Time	$t_f$			10	25	

## Notes

a. Pulse test: PW ≤ 300 μs duty cycle ≤ 2%..

**TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)**

**TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)****Source-Drain Diode Forward Voltage****On-Resistance vs. Gate-to-Source Voltage****Threshold Voltage****Single Pulse Power****Normalized Thermal Transient Impedance, Junction-to-Ambient**